**Hobbies & Interests**
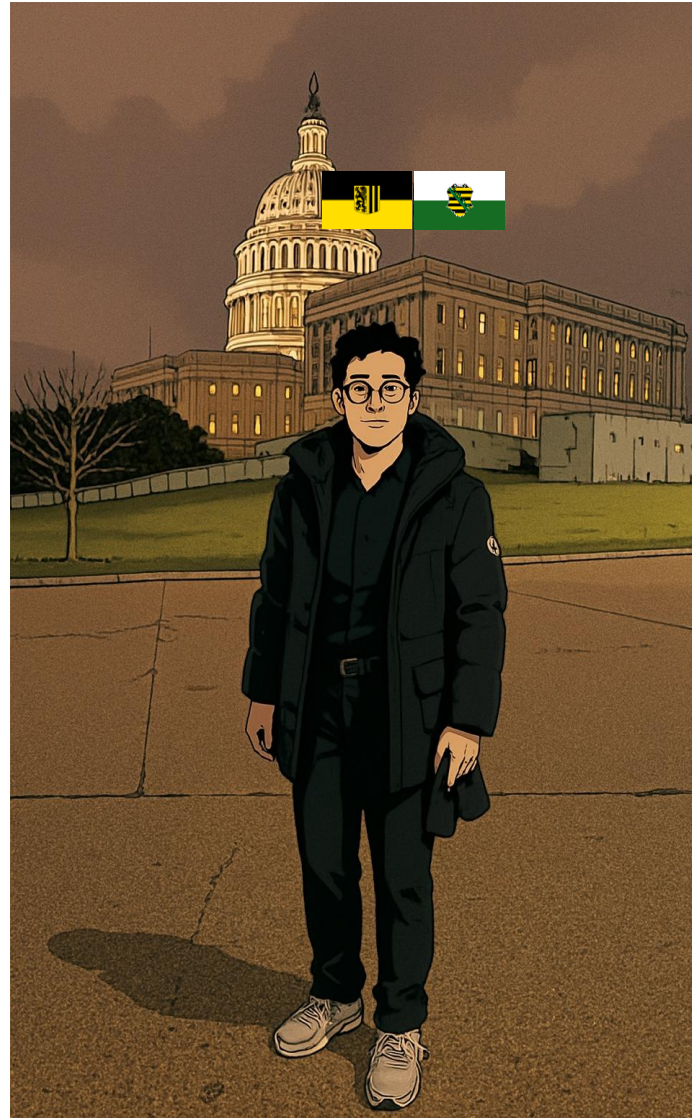
Long-distance running

Hiking

Cycling

European history
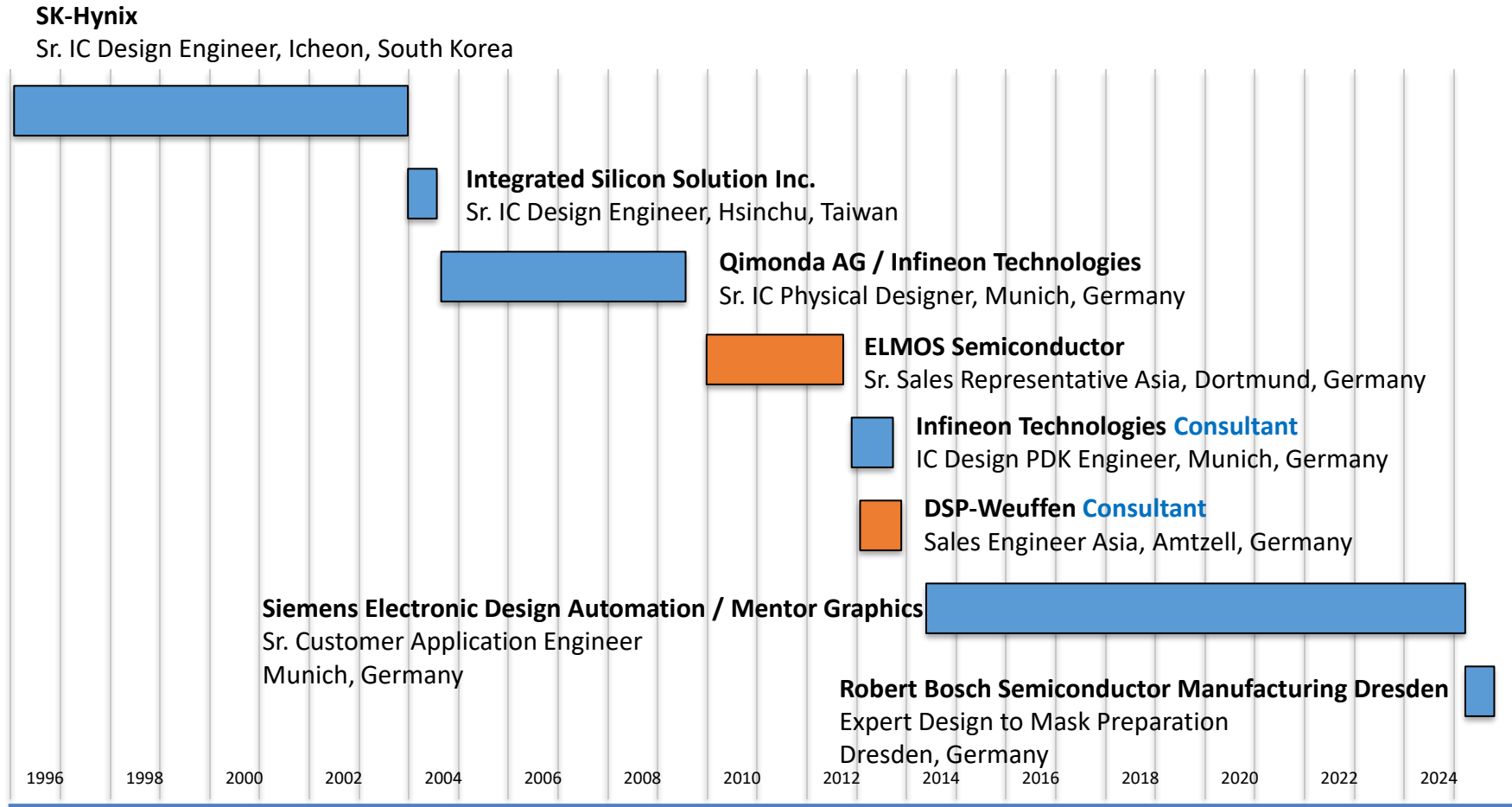


*Be Joyful always pray continually
Give thanks in all circumstance*

*Happy*

*Dream big*

# Career Timeline

**SK-Hynix**
Sr. IC Design Engineer, Icheon, South Korea

**Integrated Silicon Solution Inc.**
Sr. IC Design Engineer, Hsinchu, Taiwan

**Qimonda AG / Infineon Technologies**
Sr. IC Physical Designer, Munich, Germany

**ELMOS Semiconductor**
Sr. Sales Representative Asia, Dortmund, Germany

**Infineon Technologies** Consultant
IC Design PDK Engineer, Munich, Germany

**DSP-Weuffen** Consultant
Sales Engineer Asia, Amtzell, Germany

**Siemens Electronic Design Automation / Mentor Graphics**
Sr. Customer Application Engineer
Munich, Germany

**Robert Bosch Semiconductor Manufacturing Dresden**
Expert Design to Mask Preparation
Dresden, Germany

Companies

1996  1998  2000  2002  2004  2006  2008  2010  2012  2014  2016  2018  2020  2022  2024

**Year (02.1996 – 10.2025)**

# CAREER SNAPSHOT

Munich, Germany

DAUERAUFENTHALT–EU

Kyung Wook Park — Senior Semiconductor Expert

Nearly 3 decades — IC Design • Physical Design • Verification • Tape-Out • EDA • Sales

## TECHNICAL EXPERTISE

• Design-to-Mask & Tape-Out: OPC/RET, MDP, mask assembly, DFM, 300mm fab integration (Bosch)

• Physical Verification (Calibre): DRC | LVS | PERC | OPC RET | SmartFILL | Pattern Matching

• Memory & Mixed-Signal: DDR1/DDR2, bank-cell arrays, PLL/timing, I/O, Sense Amps, Voltage Generators

• Advanced Processes: TSMC N3E/N7/N16/N28, GF 45/28/22, Intel nodes, Samsung 14nm FinFET

• EDA & Automation: Siemens Calibre, Cadence Virtuoso, Pegasus, SKILL, Synopsys ICC2 P&R;, Python, TCL

## CUSTOMER & BUSINESS IMPACT

• Siemens EDA (Calibre CAE): Customer support, training, tool adoption (Intel, GF, Infineon, Apple, ST)

• ELMOS Senior Sales Manager Asia: Tier-1 customers; €15M revenue in ultrasonic ICs

• DSP-Weuffen (ADAS Sales): Developed China/Korea market for multi-camera SoCs

• Cross-functional leadership: Sales, Product, Design, QA, Logistics, Finance coordination

• Secured key accounts and led successful annual price negotiations, maintaining and growing revenue stream

## ACHIEVEMENTS & RECOGNITION

• Patents: 2 US + 12 Korean patents (DRAM & design automation)

• Awards: Key Talent Award (€20,000), Outstanding Achievement, Best Product Award

• Recognized expert: Memory design simulation, verification, DFM SmartFILL/OPC/DRC writer, physical design methodologies, ASICs

## GLOBAL EXPERIENCE & CORE STRENGTHS

• Global footprint: Germany, Korea, Taiwan, China; EU/Asia customer engagements

• Languages: English (C2), Korean (native), German (B2)

• Core strengths: End-to-End lifecycle, cross-functional leadership, automation & problem-solving